Technical Data Sheet

FeedBond® AP-2100-C1(AB)

Two Component Adhesive

Description:

FeedBond® AP-2100-C1(AB) is a two-component, high-temperature fast-curing epoxy resin, designed for semiconductor, optical fiber and other applications. With excellent operating performance and reliability.

A Parts Item	Unit	Typical Condition
Appearance	-	Transparent
Viscosity	Cps	3000
B Parts Item	**Unit**	**Typical Condition**
Appearance	-	Amber
Viscosity	Cps	2000
Recommended Curing Condition & Properties		
Mix Ratio (With B Parts Hardener)	g	10:1
Work life (10 : 1 Mix Ratio/25℃)	Hour	3
Glass Transition Temperature	℃	133
Hardness, Shore D	-	80
Grind	-	<15um
Hot plate Curing condition (10 :1 Mix Ratio)	1 min @150℃ 5 min @120℃ 10 min @100℃ 30 min @80℃	
Die Shear Strength @ 25℃ >3 kg/die	45mil × 45mil Si die on Ag LF	
Die Shear Strength @ 150℃ >2.5 kg/die		

PHYSIOCHEMICAL PROPERTIES- POST CURE		TEST DESCRIPTION
Coefficient of Thermal Expansion		TMA Expansion Mode
Below Tg(α1)	45ppm/℃	
Above Tg(α2)	189 ppm/℃	
Storage Modulus @25℃ @150℃ @250℃	 2356MPa 49MPa 40MPa	Dynamic Mechanical Thermal Analysis using <1.6mm thick specimen
TGA Weight Loss @200℃ @250℃ @300℃	 0.13% 0.30% 0.58%	TGA Thermal Scan

Precautions:

Due to the temperature change or storage for long time, sometimes A part will cause viscosity to rise or appear lumpy. Put A part into the oven and heat it for 60°C and 30 minutes, can be used normally after mixing well.

Please stir well before use.

General Information

For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).

Storage

Store product in the unopened container in a dry location. Optimal Storage: Room temperature(18~28℃) 12 months. Storage below 5°C or greater than 30°C can adversely affect product properties.
Material removed from containers may be contaminated. Do not return product to the original container